



## Material Content Data Sheet



<b>Sales Product Name</b>		BSZ050N03LS G		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA000896756						
<b>Package</b>		PG-TSDSON-8-22		<b>Weight*</b>		36.53 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.213	3.32	3.32	33191	33191
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		65	
	non noble metal	zinc	7440-66-6	0.009	0.03		259	
	non noble metal	iron	7439-89-6	0.189	0.52		5183	
wire	non noble metal	copper	7440-50-8	7.689	21.05	21.61	210470	215977
	noble metal	gold	7440-57-5	0.187	0.51	0.51	5130	5130
encapsulation	organic material	carbon black	1333-86-4	0.036	0.10		998	
	plastics	epoxy resin	-	1.878	5.14		51396	
	inorganic material	silicondioxide	60676-86-0	16.315	44.66	49.90	446601	498995
leadfinish	non noble metal	tin	7440-31-5	0.370	1.01	1.01	10130	10130
plating	noble metal	silver	7440-22-4	0.081	0.22	0.22	2212	2212
solder	non noble metal	tin	7440-31-5	0.069	0.19		1890	
	non noble metal	lead	7439-92-1	1.312	3.59	3.78	35914	37804
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		32	
	non noble metal	zinc	7440-66-6	0.005	0.01		129	
	non noble metal	iron	7439-89-6	0.094	0.26		2572	
	non noble metal	copper	7440-50-8	3.816	10.45	10.72	104454	107187
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.001	0.00		27	
	non noble metal	zinc	7440-66-6	0.004	0.01		107	
	non noble metal	iron	7439-89-6	0.078	0.21		2145	
	non noble metal	copper	7440-50-8	3.182	8.71	8.93	87095	89374
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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